



Product Change Notification: MFOL-08LAOX415

Date:

15-Jun-2026

Product Category:

Switching Regulators

Notification Subject:

CCB 8336 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP16311T-E/MS, MCP16311-E/MS, MCP16312-E/MS, MCP16312T-E/MS, and MCP16312-E/MS-5 catalog part numbers (CPN) available in 8L MSOP (3x3mm) package at MTAI assembly site.

Affected CPNs:

[MFOL-08LAOX415_Affected_CPN_06152026.pdf](#)

[MFOL-08LAOX415_Affected_CPN_06152026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for MCP16311T-E/MS, MCP16311-E/MS, MCP16312-E/MS, MCP16312T-E/MS, and MCP16312-E/MS-5 catalog part numbers (CPN) available in 8L MSOP (3x3mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No

Wire Material	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS-free)	8390A (PFAS-free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No
Lead-Frame DAP Surface Prep	Ag	Bare Cu	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 14 September 2026 (date code: 2638)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	September 2026				
Work Week	23	24	25	26	27		36	37	38	39	40
Qual Report Availability			X								
Final PCN Issue Date			X								
Estimated Implementation Date									X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 15, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance

regarding the material content of the applicable product.

Attachments:

[PCN_MFOL-08LAOX415_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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